



**THE DATASHEET OF
SN74F169DR**



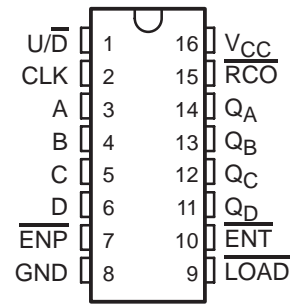
SN74F169

SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTER

SDFS089 – MARCH 1987 – REVISED OCTOBER 1993

- Fully Synchronous Operation for Counting and Programming
- Internal Look-Ahead Circuitry for Fast Counting
- Carry Output for N-Bit Cascading
- Fully Independent Clock Circuit
- Package Options Include Plastic Small-Outline Packages and Standard Plastic 300-mil DIPs

D OR N PACKAGE
(TOP VIEW)



description

This synchronous, presettable, 4-bit up/down binary counter features an internal carry look-ahead circuitry for cascading in high-speed counting applications. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable ($\overline{\text{ENP}}$, $\overline{\text{ENT}}$) inputs and internal gating. This mode of operation eliminates the output counting spikes that are normally associated with asynchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

This counter is fully programmable; that is, it may be preset to any number between 0 and its maximum count. The load-input circuitry allows loading with the carry-enable output of cascaded counters. As loading is synchronous, setting up a low level at the load ($\overline{\text{LOAD}}$) input disables the counter and causes the outputs to agree with the data inputs after the next clock pulse.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous application without additional gating. Instrumental in accomplishing this function are two count-enable ($\overline{\text{ENP}}$, $\overline{\text{ENT}}$) inputs and a ripple-carry (RCO) output. Both $\overline{\text{ENP}}$ and $\overline{\text{ENT}}$ must be low to count. The direction of the count is determined by the level of the up/down ($\overline{\text{U/D}}$) input. When $\overline{\text{U/D}}$ is high, the counter counts up; when low, it counts down. Input $\overline{\text{ENT}}$ is fed forward to enable the RCO. RCO thus enabled will produce a low-level pulse while the count is zero (all inputs low) counting down or maximum (9 or 15) counting up. This low-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at $\overline{\text{ENP}}$ or $\overline{\text{ENT}}$ are allowed regardless of the level of the clock input. All inputs are diode clamped to minimize transmission-line effects, thereby simplifying system design.

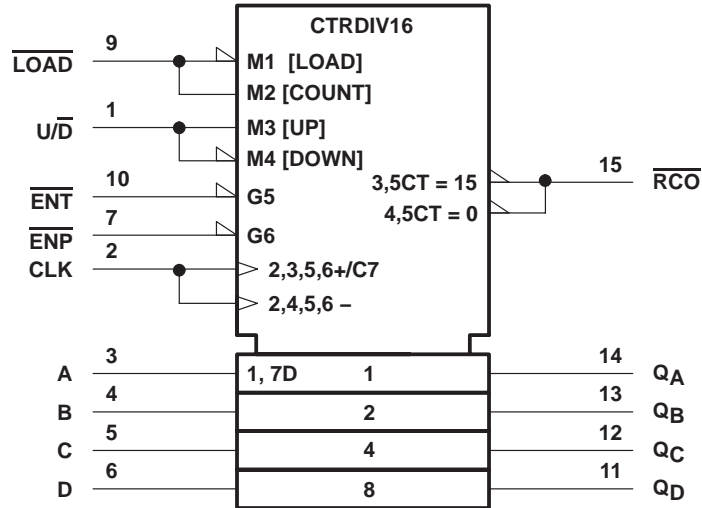
The SN74F169 features a fully independent clock circuit. Changes at control inputs ($\overline{\text{ENP}}$, $\overline{\text{ENT}}$, $\overline{\text{LOAD}}$ or $\overline{\text{U/D}}$) that will modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) will be dictated solely by the conditions meeting the setup and hold times.

The SN74F169 is characterized for operation from 0°C to 70°C.

SN74F169 SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTER

SDFS089 – MARCH 1987 – REVISED OCTOBER 1993

logic symbol†

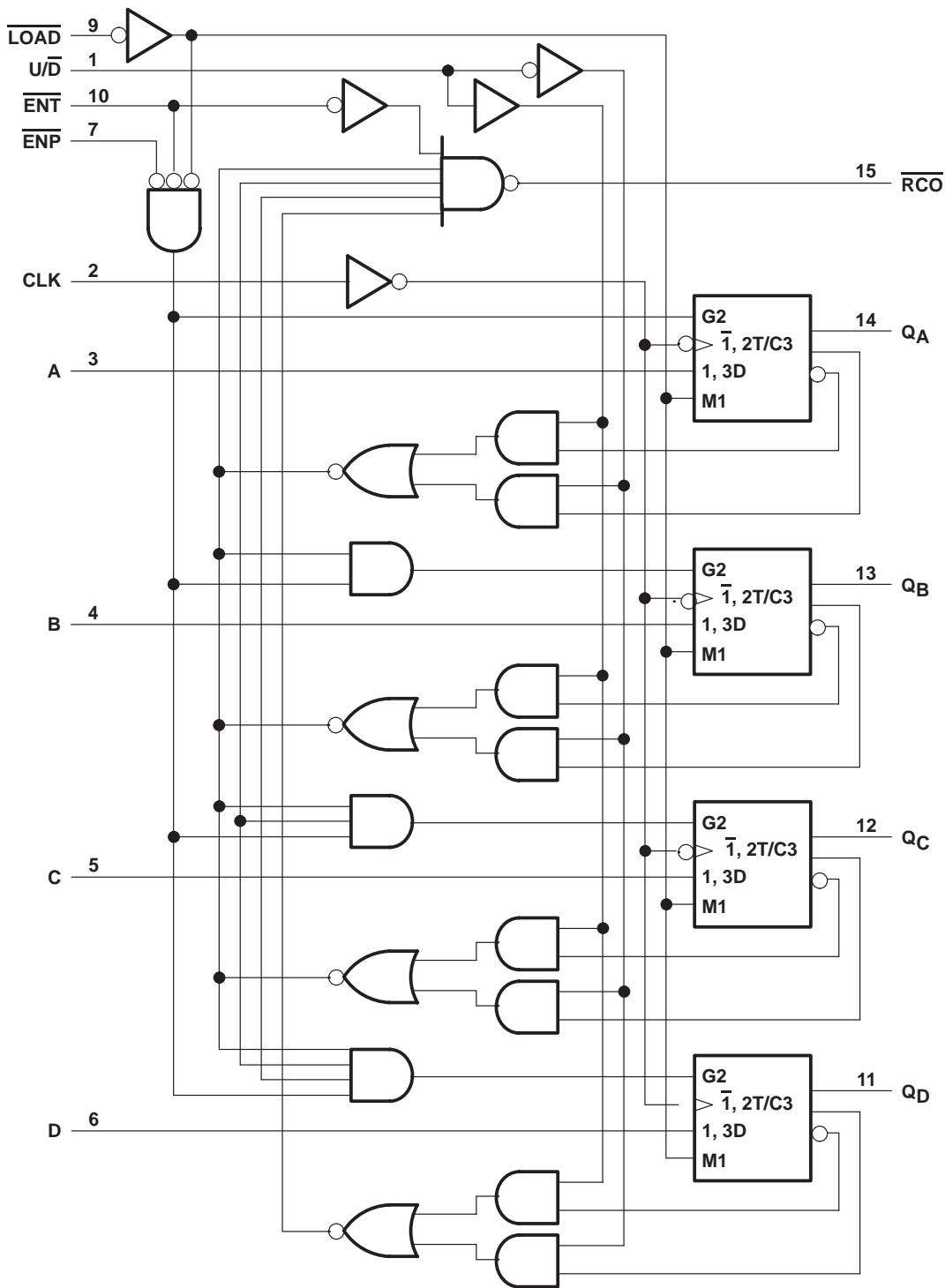


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SN74F169 SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTER

SDFS089 – MARCH 1987 – REVISED OCTOBER 1993

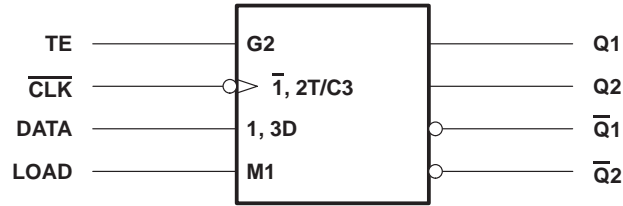
logic diagram (positive logic)



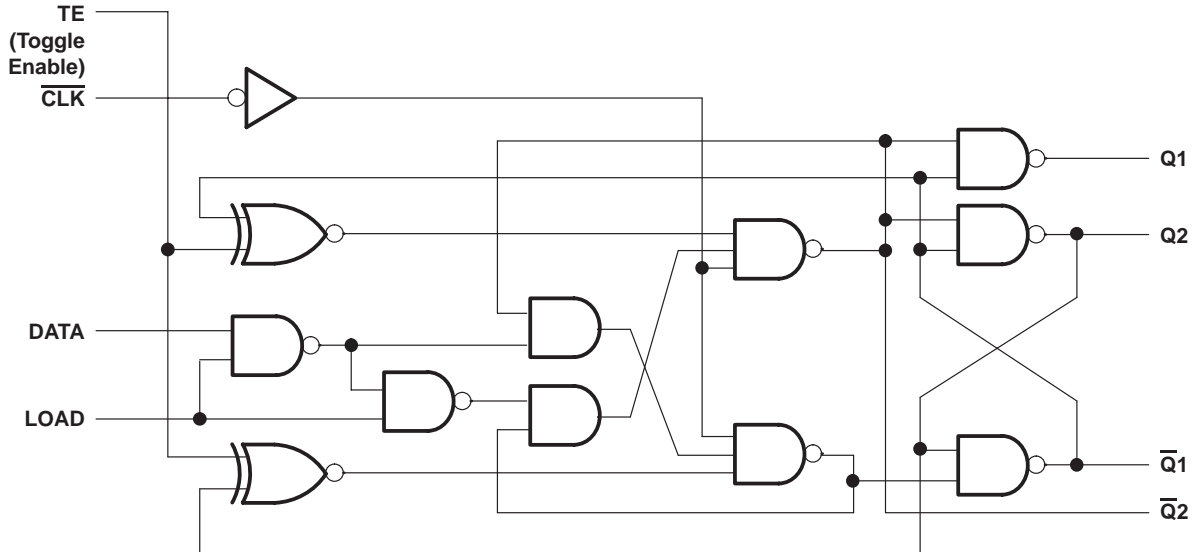
SN74F169 SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTER

SDFS089 – MARCH 1987 – REVISED OCTOBER 1993

logic symbol, each flip-flop



logic diagram, each flip-flop (positive logic)



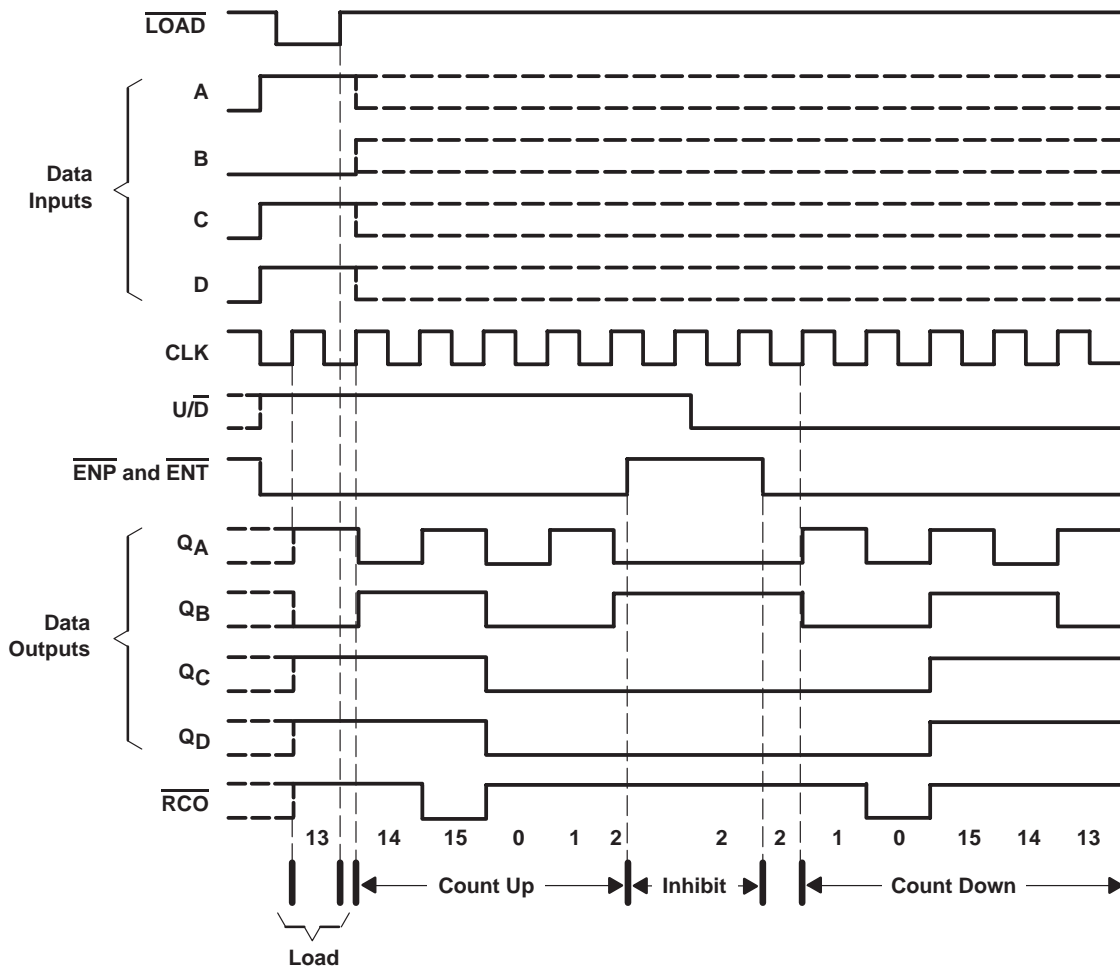
FUNCTION TABLE
(each flip-flop)

COUNTER INPUTS		FLIP-FLOP INPUTS				OUTPUTS	
LOAD	CLK	LOAD	TE	CLK	DATA	Q	Q̄
L	↑	H	L	↓	H	H	L
L	↑	H	L	↓	L	L	H
H	↑	L	H	↓	X	Q̄ ₀	Q ₀
H	↑	L	L	↓	X	Q ₀	Q̄ ₀

typical load, count, and inhibit sequences

Illustrated below is the following sequence:

1. Load (preset) to binary thirteen
2. Count up to fourteen, fifteen (maximum), zero, one, and two
3. Inhibit
4. Count down to one, zero (minimum), fifteen, fourteen, and thirteen



SN74F169

SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTER

SDFS089 – MARCH 1987 – REVISED OCTOBER 1993

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–1.2 V to 7 V
Input current range	–30 mA to 5 mA
Voltage range applied to any output in the high state	–0.5 V to V_{CC}
Current into any output in the low state	40 mA
Operating free-air temperature range	0°C to 70°C
Storage temperature range	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

	MIN	NOM	MAX	UNIT
V_{CC} Supply voltage	4.5	5	5.5	V
V_{IH} High-level input voltage	2			V
V_{IL} Low-level input voltage			0.8	V
I_{IK} Input clamp current			–18	mA
I_{OH} High-level output current			–1	mA
I_{OL} Low-level output current			20	mA
T_A Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
V_{OH}	$V_{CC} = 4.5$ V, $I_{OH} = -1$ mA	2.5	3.4		V
	$V_{CC} = 4.75$ V, $I_{OH} = -1$ mA	2.7			
V_{OL}	$V_{CC} = 4.5$ V, $I_{OL} = 20$ mA		0.3	0.5	V
I_I	$V_{CC} = 5.5$ V, $V_I = 7$ V			0.1	mA
I_{IH}	$V_{CC} = 5.5$ V, $V_I = 2.7$ V			20	μA
I_{IL}	\overline{ENT}	$V_{CC} = 5.5$ V, $V_I = 0.5$ V		–1.2	mA
	All others			–0.6	
I_{OS}^{\S}	$V_{CC} = 5.5$ V, $V_O = 0$	–60		–150	mA
I_{CC}	$V_{CC} = 5.5$ V, See Note 2		38	52	mA

‡ All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: I_{CC} is measured after applying a momentary 4.5 V, then ground, to the clock input with B and \overline{ENT} inputs high and all other inputs low.



SN74F169

SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTER

SDFS089 – MARCH 1987 – REVISED OCTOBER 1993

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V _{CC} = 5 V, T _A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
f _{clock}	Clock frequency		0	100	0	90	MHz
t _w	Pulse duration	CLK high or low	5		5.5		ns
t _{su}	Setup time	Data before CLK↑	High or low	4	4.5		ns
		$\overline{\text{LOAD}}$ before CLK↑	High or low	8	9		
		$\overline{\text{ENP}}$ and $\overline{\text{ENT}}$ before CLK↑	High or low	5	6		
		U/ $\overline{\text{D}}$ before CLK↑	High	11	12.5		
t _h	Hold time	U/ $\overline{\text{D}}$ before CLK↑	Low	7	8		ns
		Data after CLK↑	High or low	3	3.5		
		$\overline{\text{LOAD}}$ after CLK↑	High or low	0	0		
		$\overline{\text{ENP}}$ and $\overline{\text{ENT}}$ after CLK↑	High or low	0	0		
		U/ $\overline{\text{D}}$ after CLK↑	High or low	0	0		

switching characteristics (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, C _L = 50 pF, R _L = 500 Ω, T _A = 25°C			V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX†		UNIT
			MIN	TYP	MAX	MIN	MAX	
f _{max}			100	115		90		MHz
t _{PLH}	CLK	Q	2.2	6.1	8.5	2.2	9.5	ns
t _{PHL}			3.2	8.6	11.5	3.2	13	
t _{PLH}	CLK	$\overline{\text{RCO}}$	4.7	11.6	15.5	4.7	17	ns
t _{PHL}			3.2	8.1	11	3.2	12.5	
t _{PLH}	$\overline{\text{ENT}}$	$\overline{\text{RCO}}$	1.7	4.1	6	1.7	7	ns
t _{PHL}			1.7	5.6	8	1.7	9	
t _{PLH}	U/ $\overline{\text{D}}$	$\overline{\text{RCO}}$	2.7	8.1	11	2.7	12.5	ns
t _{PHL}			3.2	7.6	10.5	3.2	12	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 3: Load circuits and waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74F169D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F169DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F169DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F169DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F169DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F169DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F169N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74F169NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

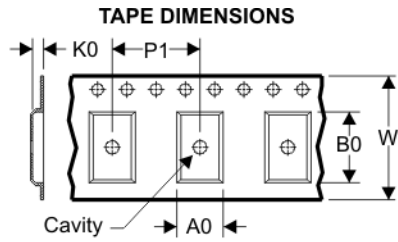
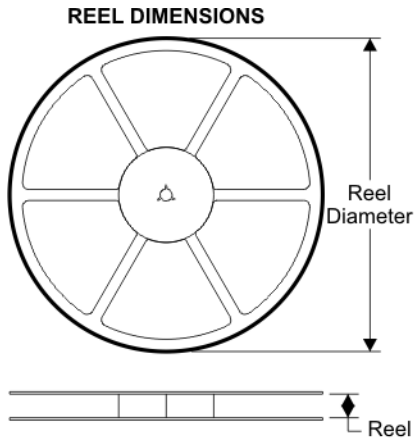
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

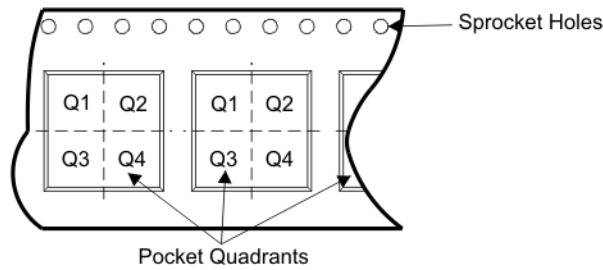
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL BOX INFORMATION



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F169DR	D	16	SITE 27	330	16	6.5	10.3	2.1	8	16	Q1

TAPE AND REEL BOX DIMENSIONS



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74F169DR	D	16	SITE 27	342.9	336.6	28.58

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

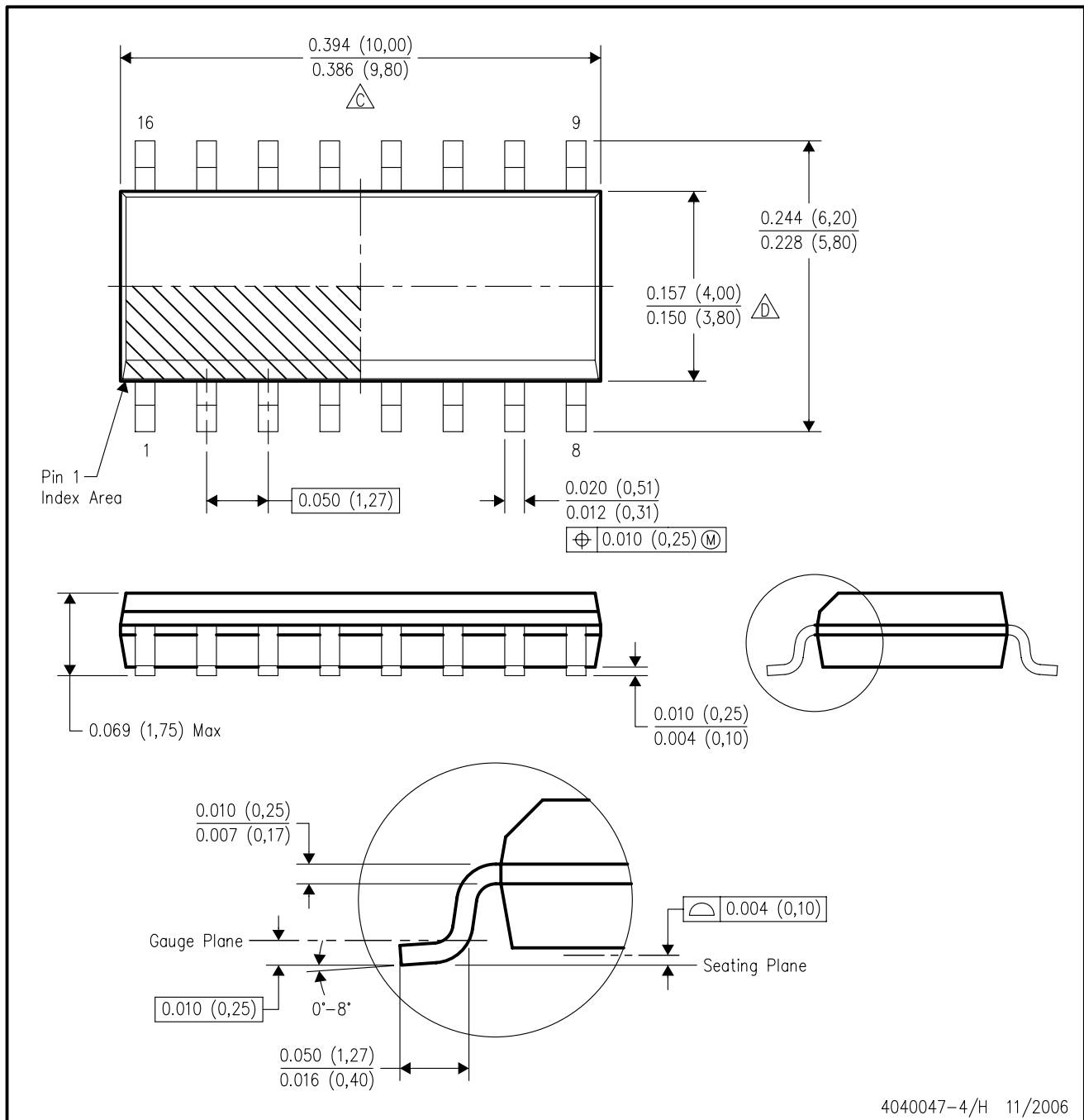
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
Low Power Wireless	www.ti.com/lpw	Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2007, Texas Instruments Incorporated

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View SN74F169DR on WIN SOURCE](#)

 [Texas Instruments](#) Information

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management